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1	2001	AD	4,597,617	7/1/86	Enochs	339	17		
\int	RADE	AE	4,604,644	8/5/86	Beckham et al.	357	080		
-		AF	4,627,151	12/9/86	Mulholland et al.	29	569		
		AG	4,628,406	12/9/86	Smith et al.	361	386		
		АН	4,649,415	3/10/87	Hebert	357	74		
		ΑĪ	4,667,220	5/19/87	Lee et al.	357	68		
	l .	AJ	4,670,770	6/2/87	Tai	357	60		
	<i>O</i> -	AK	4,685,998	8/11/87	Quinn,Daniel J. et al.	156	633		
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	G	AL	072673	8/1982	Europat				
		AM	080041	9/1982	Europat				
ļ		AN	413451	7/1990	Europat	_			
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	Ø		IBM Technical 1984, vol. 27, N		Bulletin entitled "Extend	led Pad For T	esting Package	Parts", [Dec.
	(AS	IBM Technical Aug. 1988, vol.		Bulletin entitled "Test A	nd Repair of	Direct Chip At	tach Mod	ules",
	Ģ		"Improved C4 I bulletin, vol. 32		Using Low Modulus Diel Nov. 1989.	ectric Layer",	IBM Technica	ıl Disclos	ure
	G	AT	* "Methods of Te February 1991,		s and Joining Chips to Su , GB, 32290	bstrates," 224	4 Research Dis	sclosure,	
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\ <u></u>		DOCUMENT NUMBER 4,709,468	U.S. PA	TENT DOCUMENTS				
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(d)	AA	4,709,468	12/1/87	Wilson	437	209		
ĵ.	AB	4,710,798	12/1/87	Marcantonio	357	80		
	AC	4,721,993	1/26/88	Walter	357	70		
	AD	4,751,199	6/14/88	Phy	437	209		
	AE	4,751,482	6/14/88	Fukuta et al.	333	247		
	AF	4,764,804	8/16/88	Sahara et al.	357	81		-
	AG	4,793,814	12/27/88	Zifcak et al.	439	66		
	АН	4,796,078	1/3/89	Phelps, Jr. et al.	357	68		
	AI	4,811,082	3/7/89	Jacobs et al.	357	80		
	AJ	4,814,295	3/21/89	Mehta	437	209		
F	AK	4,818,728	4/4/89	Rai et al.	437	209		
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	AM	1-293528	11/1989	Japan				
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	AB	4,855,867	8/8/89	Gazdik et al.	361	306		
	AC	4,874,721	10/17/89	Kimura et al.	437	209		
	AD	4,878,098	10/31/89	Saito et al.	357	68		
	AE	4,884,122	11/28/89	Eichelberger et al.	357	71		
	AF	4,887,148	12/12/89	Mu	357	74		
	AG	4,918,811	4/24/90	Eichelberger et al.	29	840		
	AH	4,924,353	5/3/90	Patraw	361	400		
	AI	4,926,241	5/15/90	Carey				
	AJ	4,937,203	6/26/90	Eichelberger et al.	437	51		·
(+	AK	4,937,707	6/29/90	McBride et al.	361	398		
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	AB	4,942,140	7/17/90	Ootsuki et al.	437	211		
	AC	4,967,261	10/30/90	Niki et al.	357	70		
	AD	4,989,069	1/29/91	Hawkins	357	74		
	AE	5,019,673	5/28/91	Juskey et al.	174	52.2		
	AF	5,027,191	6/25/91	Bourdelaise et al.	357	74		
	AG	5,045,921	9/3/91	Lin et al.	357	74		
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	AI	5,053,922	10/1/91	Matta et al.	361	386		
	AJ	5,123,850	6/23/92	Elder et al.	439	67		
a	AK	5,136,366	8/4/92	Worp et al.	357	72		
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0	AA	5,148,265	9/15/92	Khandros et al.	357	80		
-	AB	5,148,266	9/15/92	Khandros et al.	357	80		
1	AC	5,222,014	6/22/93	Lin	361	414		
7	AD	5,289,346	2/22/94	Carey et al.	361	777		
	AE	5,347,159	9/13/94	Khandros et al.	257	692		
	AF	5,350,947	9/27/94	Takekawa et al.	257	702		
1	AG	5,379,191	1/3/95	Carey et al.	361	777		
	АН	5,414,298	5/9/95	Grube et al.	257	690		
	AI	5,282,312*	2/1/94	DiStefano et al.	29	830		
	AJ	5,518,964*	5/21/96	DiStefano et al.	437	209		
P	AK	4,783,719	11/8/88	Jamison et al.	361	398		
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	AB	5,637,919*	6/10/97	Grabbe	257	690	
	AC	5,504,035*	4/2/96	Rostoker et al.	437	182	
	AD	5,477,082*	12/19/95	Buckley, III et al.	257	679	
	AE	5,454,160*	10/3/95	Nickel	29	840	
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	AI	4,189,825	2/80	Robillard et al.	29	574	
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0	AK	4,655,524	4/87	Etzel	339	59 M	
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G	AA	4,658,332	4/87	Baker et al.	361	398		
1	AB	4,681,654	7/87	Clementi et al.	156	630		
	AC	4,695,870	9/87	Patraw	357	74		
	AD	4,700,473	10/87	Freyman et al.	29	846		
	AE	4,772,936	9/88	Reding et al.	357	80		
1	AF	4,847,146	7/89	Yeh et al.	428	332		
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	AI	4,866,841	9/89	Hubbard	29	845		
	AJ ·	4,893,172	1/90	Matsumoto et al.	357	79		
0	AK	4,954,878	9/90	Fox et al.	357	81		
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(J	AA	4,975,765	12/90	Ackermann et al.	357	80		
	AB	4,993,954	2/91	Prevost	439	68		
	AC	5,006,673	4/91	Freyman et al.	174	255		
	AD	5,029,325	7/91	Higgins, III et al.	357	80		
	AE	5,086,337	2/92	Noro et al.	357	79		
	AF	5,117,275	5/92	Bregman	357	70		
	AG	Re: 35,119	12/12/95	Blonder, et al.	204	164		
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G	ΑI	5,210,939	5/18/93	Blonder, et al.	235	488		
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	AE	4,766,670	8/88	Godzik, et al.	29	830		
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